



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-01-11
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
A5973D013TR	S561*UD73EEA	A	ZY1A	2016-01-11
Amount		UoM	Unit type	ST ECOPACK Grade
79.52		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	4.85-3.9-1.52	8	Through-hole	
Comment	Package: HSOP 8L .150" PITCH 1.27 EXPOPAD			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	S561*UD73EEA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.023	mg	supplier	die	Silicon (Si)	7440-21-3		4.792	mg	954012	60262
				supplier	metallization	Aluminium (Al)	7429-90-5		0.032	mg	6371	402
				supplier	metallization	Tungsten (W)	7440-33-7		0.050	mg	9954	629
				supplier	Passivation	Silicon Nitride	12033-89-5		0.008	mg	1593	101
				supplier	Passivation	Silicon Oxide	7631-86-9		0.074	mg	14732	931
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.003	mg	597	38
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.024	mg	4778	302
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.003	mg	597	38
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.037	mg	7366	465
				Leadframe	Copper & Its alloys	31.077	mg	Supplier	Alloy	Copper (Cu)	7440-50-8	
Supplier	Alloy	Iron (Fe)	7439-89-6						0.734	mg	23619	9230
Supplier	Alloy	Zinc (Zn)	7440-66-6						0.041	mg	1319	516
Supplier	Alloy	Phosphorous (P)	12185-10-3						0.012	mg	386	151
Supplier	Coating	Silver (Ag)	7440-22-4						0.534	mg	17183	6715
Supplier	Coating	Silver (Ag)	7440-22-4						0.494	mg	801948	6212
Die Attach	Other inorganic materials	0.616	mg	Supplier	Glue	Epoxy resin (molecular weight <= 700g)	9003-36-5		0.050	mg	81169	629
				Supplier	Glue	Epoxy resin	68475-94-5		0.018	mg	29221	226
				Supplier	Glue	2,6-Diglycidyl phenyl allyl ether	EC 417-470-1		0.018	mg	29221	226
				Supplier	Glue	Gamma Butyrolactone	96-48-0		0.018	mg	29221	226
				Supplier	Glue	Polyoxypropylenediamine	9046-10-0		0.018	mg	29221	226
				Supplier	Bonding wire	Gold (Au)	7440-57-5		0.212	mg	1000000	2666
Bonding wire	Precious metals	0.212	mg	Supplier	Bonding wire	Gold (Au)	7440-57-5		0.212	mg	1000000	2666
				Supplier	Moulding Compound	Biphenyl epoxy resin	85954-11-6		3.304	mg	80008	41549
				Supplier	Moulding Compound	Phenol resin Novolak	26834-02-6		1.652	mg	40004	20775
				Supplier	Moulding Compound	Silica, vitreous	60676-86-0		35.885	mg	868970	451270
				Supplier	Moulding Compound	Carbon black	1333-86-4		0.207	mg	5013	2603
Encapsulation	Other inorganic materials	41.296	mg	Supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.248	mg	6005	3119
				Supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.248	mg	6005	3119
				Supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.248	mg	6005	3119
Finishing	Solder	1.296	mg	Supplier	Connection coating	Tin (Sn)	7440-31-5		1.296	mg	1000000	16298